

neardi

FD7652P WIFI Module

220P12-0

Datasheet

V1.0



Shanghai Neardi Technology Co., Ltd.

www.neardi.com

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Shanghai Neardi Technology Co., Ltd.

www.neardi.com

Tel: +86 21 20952021

Email: sales@neardi.com

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Version History

Version	Date	Illustrate
V1.0	2025/10/21	Initial Version

Contents

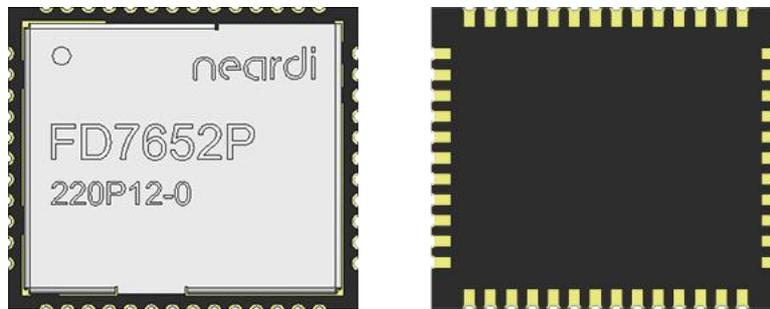
Contents	2
1 Product Overview	3
1.1 Product Introduction	4
1.2 Wi-Fi Characteristics	4
1.3 Bluetooth Characteristics	5
1.4 Block Diagram	5
1.5 Parameters	6
2 Pin Definition	7
2.1 Pin Number	7
2.2 Pin Description	7
3 Mechanical Specifications	9
3.1 Mechanical Dimensions	9
3.2 Recommended PCB Layout Footprint	9
4 Electrical Performance and Reliability	10
4.1 Recommended Operation Conditions	10
4.2 Power On/Off Sequence	10
4.3 Reliability	10
5 Interface Timing Parameters	11
5.1 PCM Interface Timing	11
6 RF Characteristics	12
6.1 2.4GHZ Wi-Fi Radio Frequency (RF) Characteristics	12
6.2 5GHZ Wi-Fi RF Characteristics	13
6.3 Bluetooth Radio Frequency (RF) Characteristics	14
7 Hardware Design Guide	16
7.1 Power Design Notice	16
7.2 Interface Design Notice	16
8 Antenna Design	18
8.1 Summarize	18
8.2 List of applicable FCC rules	18
8.3 Specific Operational Use Conditions-Antenna Placement Within the Host Platform	19
8.4 Limited Module Procedures	19
8.5 Trace Antenna Designs	19
8.6 RF Exposure Considerations	20
8.7 Antenna Type and Gain	20
8.8 End Product Labelling Compliance Information	21
8.9 Information on Test Modes and Additional Testing Requirements	21
8.10 Additional testing, Part 15 Subpart B Disclaimer	21
8.11 Manual Information to The End User	22
8.12 How to Make Changes - Important Note	22
9 Ordering, Storage, Production and Packaging	23
9.1 Ordering Model	23

9.2 Storage Conditions	23
9.3 Production Welding	23
9.4 Packing Specifications	24

1 Product Overview

1.1 Product Introduction

FD7652P is a highly integrated, low-cost combo module with high-performance and low-power. It supports Wi-Fi 6 and BLE protocol, supports Wi-Fi MAC of the final version of Wi-Fi 6 Wave2 protocol, Wi-Fi Baseband of 2T2R, and high-performance RF. It also supports PCIE, HS-UART and PCM interfaces for connection with the Host. This module also supports BLE and Wi-Fi to work in coexistence mode. It is suitable for consumer electronics such as IPC, tablet and IOT, and can also be used in fields with high reliability requirements such as industrial interconnection.



1.2 Wi-Fi Characteristics

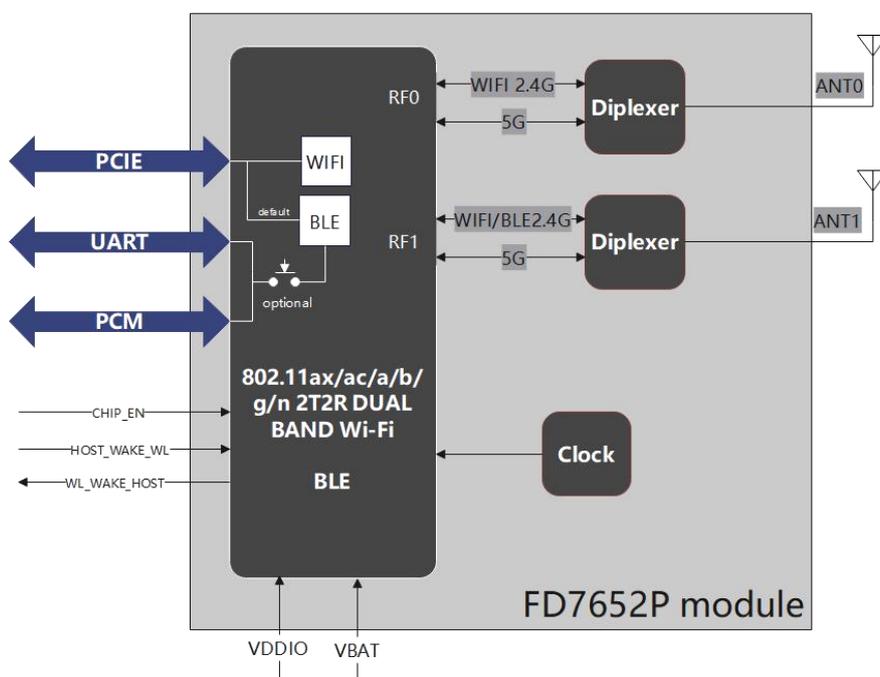
- ❖ IEEE 802.11a/b/g/n/ac/ax (supports wave-2) wireless LAN communication protocol
- ❖ IEEE 802.11 d/e/h/i/k/mc/r/v/w
- ❖ 2.4G Phy rate up to 572.4Mbps, 5G Phy rate up to 1.2Gbps; Throughput 1Gbps
- ❖ Multiple modes such as Wi-Fi STA, AP, and P2P
- ❖ Support DBDC、DBSC
- ❖ 2.4G 40MHZ, 5G 80MHz bandwidth, 2T/2R
- ❖ Up to 1024QAM modulation, supports LDPC and STBC
- ❖ UL/DL OFDMA, UL/DL MU-MIMO
- ❖ QoS, WFA WMM, WMM PS
- ❖ RSSI and CSI Reporting
- ❖ Beamformee and 4*2 Tx Beamforming、2*2/2*1 Tx Beamforming
- ❖ WPA, WPA2, WPA3 encryption and decryption, WAPI and WPS2.0
- ❖ ER, DCM to improve transceiver gain

- ❖ 20in40/80/160, 80in160 HE PPDU, Partial band MU MIMO to improve air interface utilization
- ❖ BSS Color, Spatial Reuse to improve air interface utilization
- ❖ TWT, to optimize dynamic power consumption in multi-BSS environment

1.3 Bluetooth Characteristics

- ❖ Support BLE features
- ❖ PCIE interface for BLE data transmission
- ❖ PCM/IIS interface for audio transmission
- ❖ LE 1M/LE 2M/LE LR
- ❖ Support sco and esco link
- ❖ SSP/Secure Connection
- ❖ Low power mode (sniff, sniff sub-rating)
- ❖ Support BLE/Wi-Fi coexistence

1.4 Block Diagram



Note: In the default configuration, Bluetooth UART control data and PCM audio data are multiplexed over the SDIO interface. This configuration is adequate under typical or low-traffic operating conditions. However, when Wi-Fi and Bluetooth audio operate concurrently, bandwidth contention and timing constraints on the SDIO bus may lead to instability in the Bluetooth audio stream. For systems requiring high real-time performance of

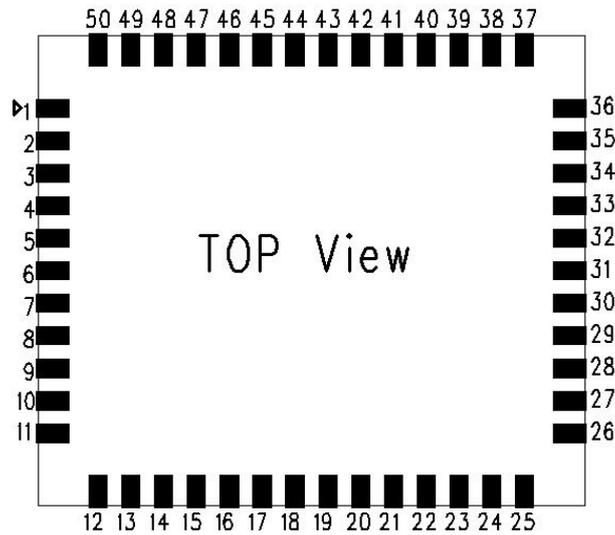
Bluetooth audio, it is recommended to route the PCM audio channel independently and interface it with the host processor through a dedicated PCM/I2S bus to ensure a stable and reliable audio path.

1.5 Parameters

Product Name	FD7652P
Product description	802.11ax/ac/a/b/g/n 2T2R dual band Wi-Fi and BLE comb module
Dimension	15.0(±0.1) mm*13.0(±0.1) mm*1.8(±0.2) mm
Power supply	VBAT: 3.0~3.6V; VDDIO: 1.62V~1.92V/3.0V~3.6V
Host interface	PCIE2.0 + UART + PCM
Footprint	LCC 50pin
Operating temperature	-30°C to 70°C
Operating humidity	10% to 90% (Non-Condensing)
Storage temperature	-40°C to 85°C

2 Pin Definition

2.1 Pin Number



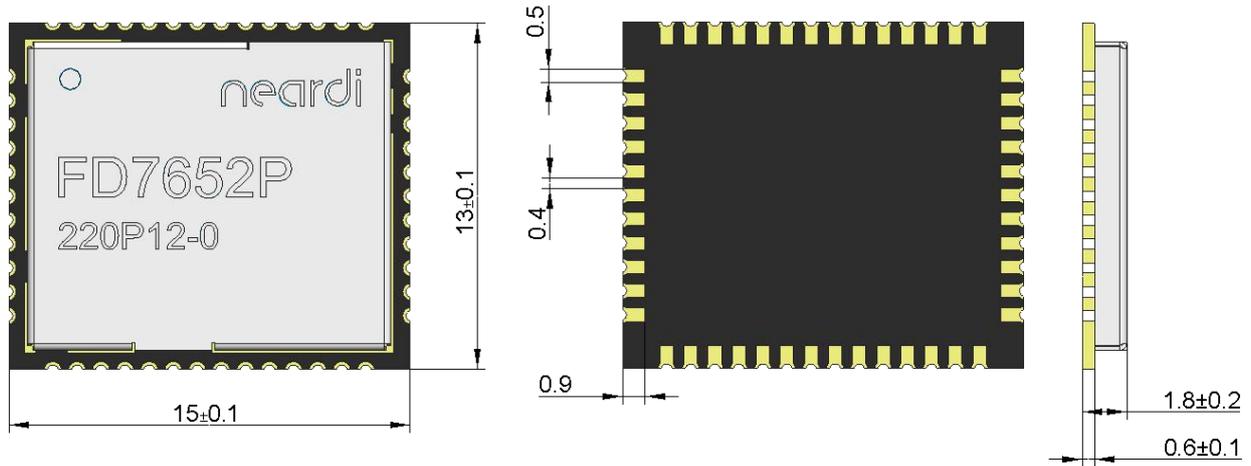
2.2 Pin Description

Pin Number	Pin Name	Pin Type	Pin Description
1	GND	G	Ground connections
2	WL_S1	RF	Wi-Fi & BLE antenna I/O port
3	GND	G	Ground connections
4	GND	G	Ground connections
5	GND	G	Ground connections
6	GND	G	Ground connections
7	GND	G	Ground connections
8	GND	G	Ground connections
9	WL_S0	RF	Wi-Fi antenna I/O port
10	GND	G	Ground connections
11	GND	G	Ground connections
12	PE_RST_N	I	PCIe host indication to reset the device
13	NC	-	Floating (Don't connected to ground)
14	NC	-	Floating (Don't connected to ground)
15	CHIP_EN	I	Module enable signal
16	WL_WAKE_HOST	I/O	Wake up signal with auto negotiation
17	NC/U1TXD	-	Floating (Don't connected to ground)
18	NC/ U1RXD	-	Floating (Don't connected to ground)
19	PCM_OUT	O	PCM Data output
20	PCM_IN	I	PCM data input

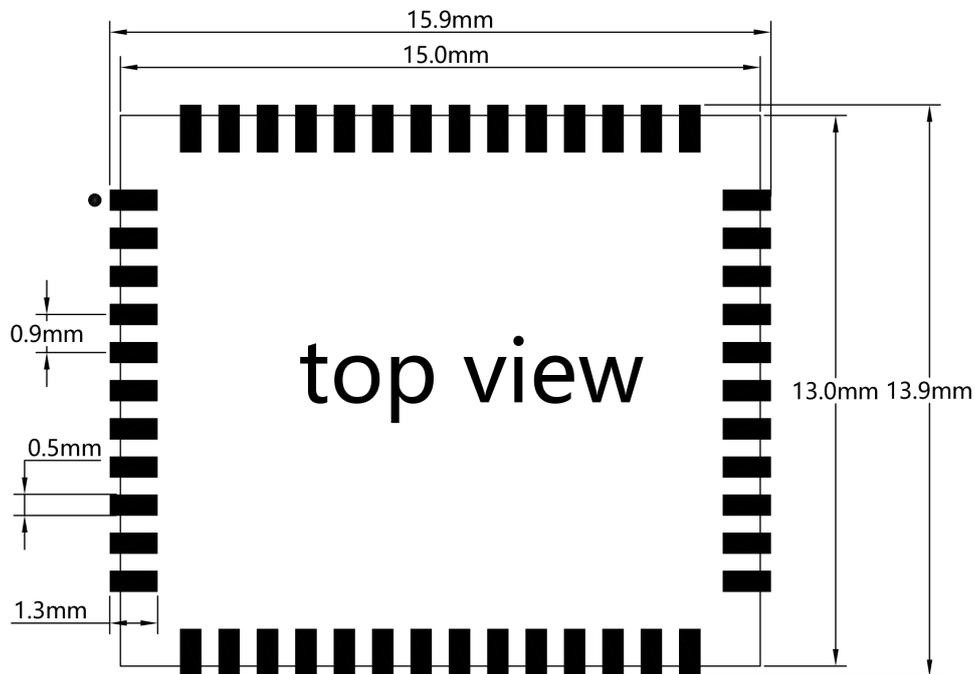
21	PCM_SYNC	I/O	PCM sync signal
22	PCM_CLK	I/O	PCM clock
23	GND	G	Ground connections
24	PE_WAKE_N	I/O	PCIE wake-up signal
25	NC	-	Floating (Don't connected to ground)
26	NC	-	Floating (Don't connected to ground)
27	GND	G	Ground connections
28	VDDIO	P	I/O Voltage supply input
29	NC	-	Floating (Don't connected to ground)
30	GND	G	Ground connections
31	NC	-	Floating (Don't connected to ground)
32	GND	G	Ground connections
33	REFCLKP	I	PCIE differential clock input-Positive
34	NC	-	Floating (Don't connected to ground)
35	REFCLKN	I	PCIE differential clock input-Negative
36	VBAT	P	Main power voltage source input
37	PE_CLKREQ_N	I/O	PCIE clock request
38	NC	-	Floating (Don't connected to ground)
39	GND	G	Ground connections
40	UART_TXD	I/O	UART TX signal
41	UART_RXD	I/O	UART RX signal
42	UART_RTS	I/O	UART DCE request to send signal
43	UART_CTS	I/O	UART DEC clear to send signal
44	PCIE_RX_N	I	PCIE receive data-Negative
45	PCIE_RX_P	I	PCIE receive data-Positive
46	PCIE_TX_N	O	PCIE transmit data-Negative
47	PCIE_TX_P	O	PCIE transmit data-Postive
48	NC	-	Floating (Don't connected to ground)
49	HOST_WAKE_WL	I/O	Wake up signal with auto negotiation
50	BT_WAKE_HOST	I/O	Wake up signal

3 Mechanical Specifications

3.1 Mechanical Dimensions



3.2 Recommended PCB Layout Footprint

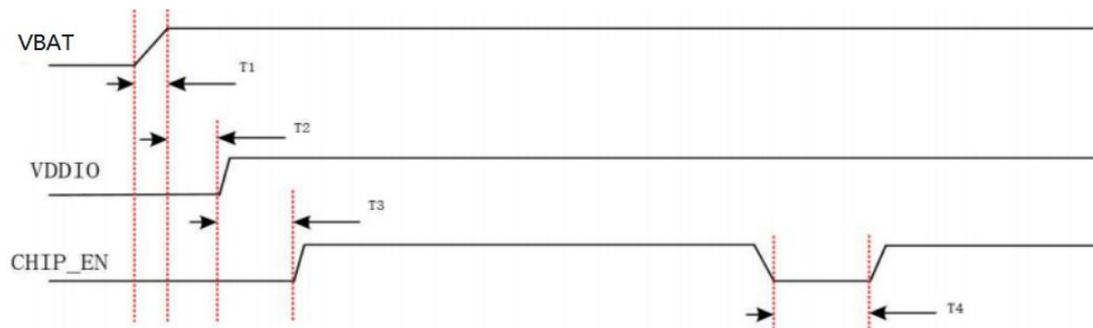


4 Electrical Performance and Reliability

4.1 Recommended Operation Conditions

Symbol	Description	Min	Type	Max	Unit
Ta	Ambient Operating Temperature	-30	25	70	°C
Antenna	External Antenna VSWR		1.92:1	2:01	
VBAT	Power Supply Voltage	3	3.3	3.6	V
	Power Supply Current	-	-	2	A
VDDIO	Digital I/O Voltage	1.62	1.8	1.92	V
		3	3.3	3.6	V
	Supply Current	-	-	150	mA

4.2 Power On/Off Sequence



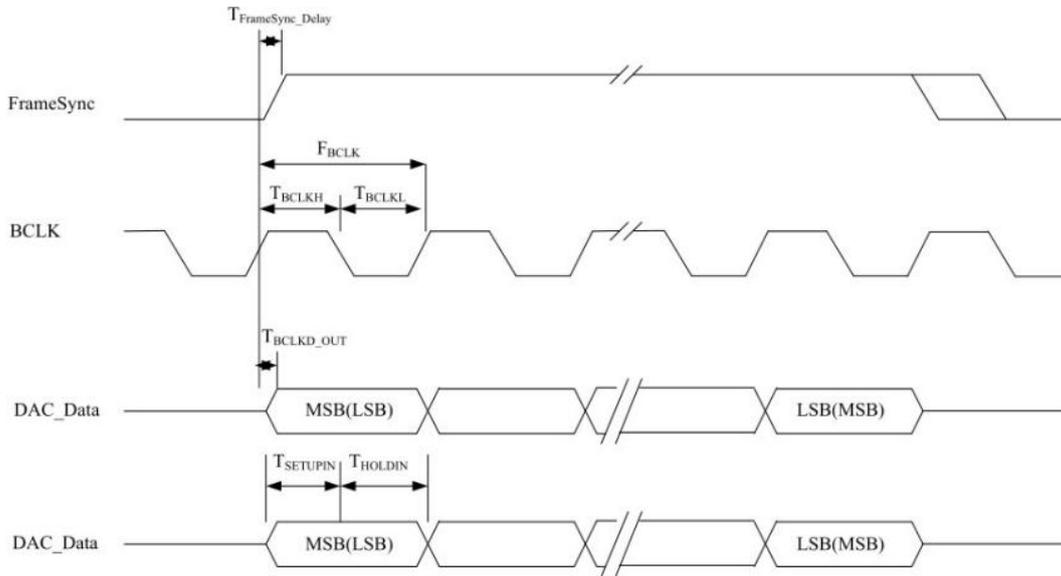
Symbol	Description	Min	Type	Max	Unit
1	VBAT Ramp up time	0.2	0.5	-	mS
2	VDDIO should be powered on after VBAT is powered on	0	-	-	mS
3	CHIP_EN should be powered on after VDDIO is powered on	0	-	-	mS
4	CHIP_EN reset time	50	-	-	mS

4.3 Reliability

Item	Test Model	Class	Level	Criteria
ESD	HBM	2	2000V	ANSI/ESDA/JEDEC JS-001-2017
	CDM	C2a	500V	ANSI/ESDA/JEDEC JS-002-2018
Latch-up	Current	II A	200mA	JEDEC STANDARD NO.78F JANUARY 2022
	Voltage	II A	1.5xVmax	JEDEC STANDARD NO.78F JANUARY 2022

5 Interface Timing Parameters

5.1 PCM Interface Timing



PCM Bus Timing

6 RF Characteristics

6.1 2.4GHZ Wi-Fi Radio Frequency (RF) Characteristics

Features	Description
Wi-Fi Standard	IEEE 802.11b/g/n/ac/ax
Frequency Range	2.4~2.4835GHz(2.4GHz ISM Band)
Channels	Ch1~Ch13
Modulation	802.11b (DSSS): CCK, DQPSK, DBPSK;
	802.11g (OFDM): BPSK, QPSK, QAM16, QAM64;
	802.11n (OFDM): BPSK, QPSK, QAM16, QAM64;
	802.11ax (OFDMA): BPSK, BPSK_DCM, QPSK, QPSK_DCM, QAM16, QAM16_DCM, QAM64, QAM256, QAM1024;
Data Rate	802.11b: 1, 2, 5.5, 11Mbps;
	802.11g: 6, 9, 12, 18, 24, 36, 48, 54Mbps;
	802.11n (HT20): MCS0~MCS7 6.5~72.2Mbps;
	802.11n (HT40): MCS0~MCS7 13.5~150Mbps;
	802.11ax (HE20): MCS0~MCS11 8~143.4Mbps;
802.11ax (HE40): MCS0~MCS11 16~286.8Mbps;	
Frequency Tolerance	≤±5ppm

2.4G Transmitter Specifications

Modulation	TX Rate	TX Power (±2dBm)	TX EVM (dB)	TX Mask
802.11b	1Mbps	20	≤35%	PASS
802.11b	11Mbps	20	≤35%	PASS
802.11g	6Mbps	20	≤-5	PASS
802.11g	54Mbps	18	≤-25	PASS
802.11n	HT20 MCS0	20	≤-5	PASS
802.11n	HT20 MCS7	18	≤-27	PASS
802.11n	HT40 MCS0	20	≤-5	PASS
802.11n	HT40 MCS7	14	≤-27	PASS
802.11ax	HE20 MCS0	20	≤-5	PASS
802.11ax	HE20 MCS11	14	≤-35	PASS
802.11ax	HE40 MCS0	20	≤-5	PASS
802.11ax	HE40 MCS11	14	≤-35	PASS

2.4G Receiver Specifications

Modulation	RX Rate	Min Input Level (dBm)	Max Input Level (dBm)	PER
802.11b	1Mbps	≤-96	-20	8%

802.11b	11Mbps	≤-87	-20	8%
802.11g	6Mbps	≤-92	-20	10%
802.11g	54Mbps	≤-75	-20	10%
802.11n	HT20 MCS0	≤-92	-20	10%
802.11n	HT20 MCS7	≤-72	-20	10%
802.11n	HT40 MCS0	≤-89	-20	10%
802.11n	HT40 MCS7	≤-70	-20	10%
802.11ax	HE20 MCS0	≤-92	-20	10%
802.11ax	HE20 MCS11	≤-60	-20	10%
802.11ax	HE40 MCS0	≤-89	-20	10%
802.11ax	HE40 MCS11	≤-58	-20	10%

6.2 5GHZ Wi-Fi RF Characteristics

Conditions: VBAT=3.3V; VDDIO=1.8V; Ta:25°C

Features	Description
Wi-Fi Standard	IEEE 802.11a/n/ac/ax
Frequency Range	5.15~5.25GHz; 5.25~5.35GHz; 5.47~5.73GHz; 5.735~5.835GHz (5GHz ISM Band)
Channels	Ch36,Ch40, Ch44, Ch48; Ch52~Ch64; Ch100~Ch140; Ch149~Ch165
Modulation	802.11a (OFDM): BPSK, QPSK, QAM16, QAM64;
	802.11n (OFDM): BPSK, QPSK, QAM16, QAM64;
Date Rate	802.11ac (OFDM): BPSK, QPSK, QAM16, QAM64, QAM256;
	802.11ax (OFDMA): BPSK, BPSK_DCM, QPSK, QPSK_DCM, QAM16, QAM16_DCM, QAM64, QAM256, QAM1024;
Date Rate	802.11a: 6, 9, 12, 18, 24, 36, 48, 54Mbps;
	802.11n (HT20): MCS0~MCS7: 6.5~72.2Mbps;
	802.11n (HT40): MCS0~MCS7: 13.5~150Mbps;
	802.11ac (VHT20): MCS0~MCS8: 6.5~86.7Mbps;
	802.11ac (VHT40): MCS0~MCS9: 13.5~200Mbps;
Date Rate	802.11ac (VHT80): MCS0~MCS9: 29.3~433.3Mbps;
	802.11ax (HE20): MCS0~MCS11: 8~143.4Mbps;
	802.11ax (HE40): MCS0~MCS11: 16~286.8Mbps;
Date Rate	802.11ax (HE80): MCS0~MCS11: 34~600.5Mbps;
	802.11ax (HE80): MCS0~MCS11: 34~600.5Mbps;
Frequency Tolerance	≤±5ppm

5G Transmitter Specifications

Modulation	TX Rate	TX Power(±2dBm)	TX EVM (dB)	TX Mask
802.11a	6Mbps	19	≤-5	PASS
802.11a	54Mbps	17	≤-25	PASS
802.11n	HT20 MCS0	19	≤-5	PASS
802.11n	HT20 MCS7	17	≤-27	PASS

802.11n	HT40 MCS0	19	≤-5	PASS
802.11n	HT40 MCS7	17	≤-27	PASS
802.11ac	VHT20 MCS0	19	≤-5	PASS
802.11ac	VHT20 MCS8	14	≤-30	PASS
802.11ac	VHT40 MCS0	19	≤-5	PASS
802.11ac	VHT40 MCS9	14	≤-32	PASS
802.11ac	VHT80 MCS0	18	≤-5	PASS
802.11ac	VHT80 MCS9	13	≤-32	PASS
802.11ax	HE20 MCS0	19	≤-5	PASS
802.11ax	HE20 MCS11	12	≤-35	PASS
802.11ax	HE40 MCS0	19	≤-5	PASS
802.11ax	HE40 MCS11	12	≤-35	PASS
802.11ax	HE80 MCS0	18	≤-5	PASS
802.11ax	HE80 MCS11	11	≤-35	PASS

5G Receiver Specifications

Modulation	RX Rate	Min Input Level (dBm)	Max Input Level (dBm)	PER
802.11a	6Mbps	-91	-20	10%
802.11a	54Mbps	-74	-20	10%
802.11n	HT20 MCS0	-91	-20	10%
802.11n	HT20 MCS7	-71	-20	10%
802.11n	HT40 MCS0	-88	-20	10%
802.11n	HT40 MCS7	-69	-20	10%
802.11ac	VHT20 MCS0	-91	-20	10%
802.11ac	VHT20 MCS8	-67	-20	10%
802.11ac	VHT40 MCS0	-88	-20	10%
802.11ac	VHT40 MCS9	-63	-20	10%
802.11ac	VHT80 MCS0	-85	-20	10%
802.11ac	VHT80 MCS9	-59	-20	10%
802.11ax	HE20 MCS0	-91	-20	10%
802.11ax	HE20 MCS11	-60	-20	10%
802.11ax	HE40 MCS0	-89	-20	10%
802.11ax	HE40 MCS11	-58	-20	10%
802.11ax	HE80 MCS0	-86	-20	10%
802.11ax	HE80 MCS11	-53	-20	10%

6.3 Bluetooth Radio Frequency (RF) Characteristics

Conditions: VBAT=3.3V; VDDIO=1.8V; Ta:25°C

Features	Description
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Bluetooth Standard	BLE
Frequency Range	2.4~2.4835GHz
Channels	Bluetooth Classic: Ch0~Ch78 (For 1MHz Channels); Bluetooth Low Energy: Ch0~Ch39 (For 2MHz Channels);
Modulation	LE_125Kbps: GFSK (Coded_S=8); LE_500Kbps: GFSK (Coded_S=2); LE_1Mbps: GFSK (Uncoded); LE_2Mbps: GFSK (Uncoded);

Bluetooth Transmitter Specifications

Item	TX Power (dBm)		
	Min	Type	Max
LE_125/500K	6	8	10
LE_1M	6	8	10
LE_2M	6	8	10

Bluetooth Receiver Specifications

Item	Sensitivity (dBm)		Max Input Level (dBm)
	Input Level (Typ)	BER	Input Level (Typ)
BLE	<-88	30.80%	-20dBm

7 Hardware Design Guide

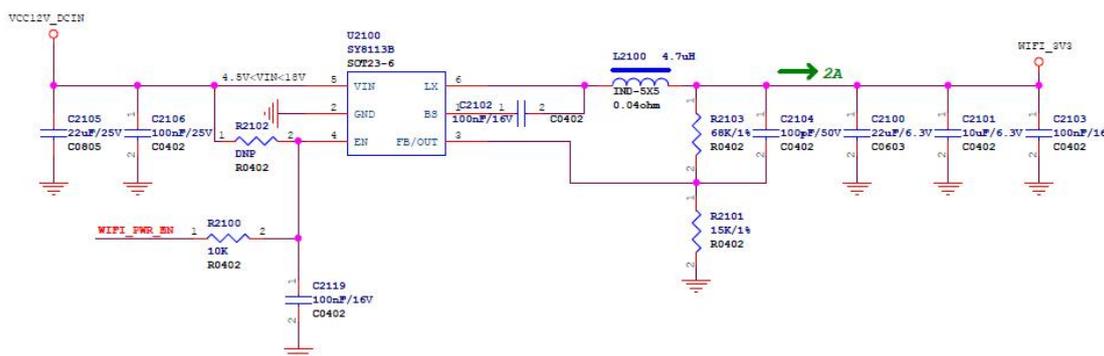
7.1 Power Design Notice

7.1.1 Voltage Requirement

The main power supply (VBAT) input range of the module is 3.3V+/-10%, and the interface VDDIO supports two level ranges, 1.8V+/-10% or 3.3V+/-10%. Due to the ripple of the main power can affect the RF performance of Wi-Fi and Bluetooth, therefore the power supply ripple VPP is required to be less than 50mV.

7.1.2 Current/Power Supply Reference Requirement

Under different standards, when Wi-Fi transmits continuously, The 3.3V power converter must be able to provide 2.0A current and fast transient response (when the transient current change rate is 80mA/us, the voltage drop is less than 100mV).

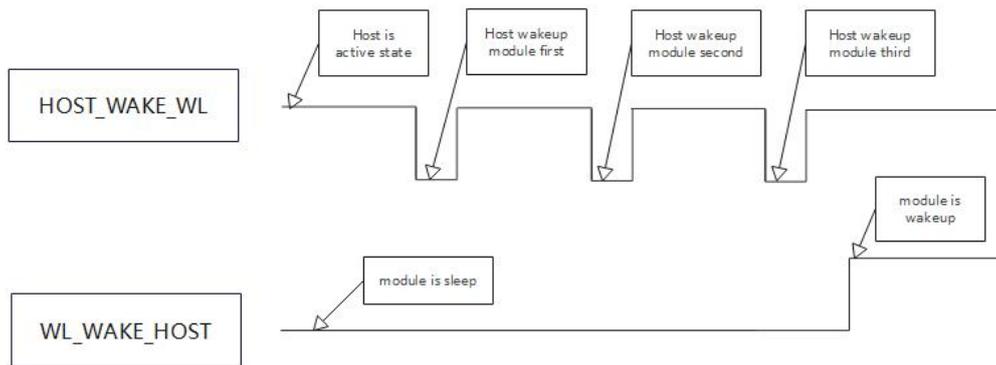


For the power on/off sequence of the module, please refer to the requirements in the "4.3 Power On/Off Sequence" chapter.

7.2 Interface Design Notice

7.2.1 Wake-up Signals

This module require two GPIOs as handshake signals with the host controller. As default, for example, WL_WAKE_HOST is the output signal "CP wakes up the Host", and HOST_WAKE_WL is the input signal "Host wakes up CP". Wi-Fi and Bluetooth use the same handshake signal. The working mechanism is as follows.

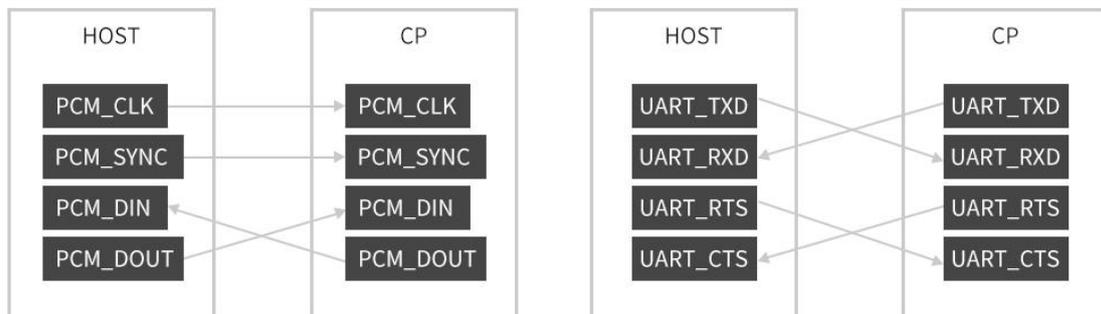


7.2.2 HCI Commend Interface

The Bluetooth supports PCIE and HS-UART (4Mbps) as HCI (Host Controller Interface). PCIE is used as HCI by default, which means the HS-UART port does not need in the HOST controller.

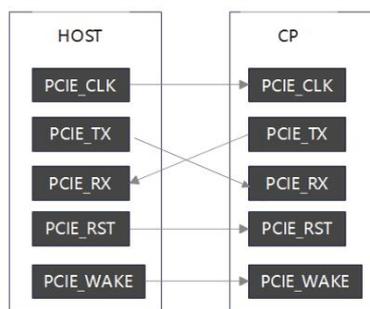
7.2.3 PCM and UART Interface

As shown in the figure below, the PCM bus and UART bus and data lines between the Host and the module need to be cross-connected.



7.2.4 PCIe Interface

PCIe data lines need to be cross-connected between HOST and CP.



8 Antenna Design

8.1 Summarize

This device complies with part 15 of the FCC Rules. Operation is subject to the following two conditions:

- (1) This device may not cause harmful interference, and
- (2) this device must accept any interference received, including interference that may cause undesired operation.

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy and, if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following

measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

This modular has been tested and found to comply with part 15 requirements for Modular Approval.

- FCC Caution: Any changes or modifications not expressly approved by the party responsible for compliance could void the user's authority to operate the equipment. This transmitter must not be co-located or operating in conjunction with any other antenna or

transmitter.

- Integration instructions for host product manufacturers according to KDB 996369 D03

OEM Manual v01r01

8.2 List of applicable FCC rules

CFR 47 FCC Part 15 Subpart C and Subpart F has been investigated. It is applicable to the modular transmitter

8.3 Specific Operational Use Conditions-Antenna Placement Within the Host Platform

The module is tested for standalone mobile RF exposure use condition.

- The antenna must be installed such that 20cm is maintained between the antenna and users,
- The transmitter module may not be co-located with any other transmitter or antenna. In the event that these conditions cannot be met (for example certain laptop configurations or co-location with another transmitter), then the FCC authorization is no longer considered valid and the FCC ID cannot be used on the final product. In these

circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

8.4 Limited Module Procedures

Not applicable

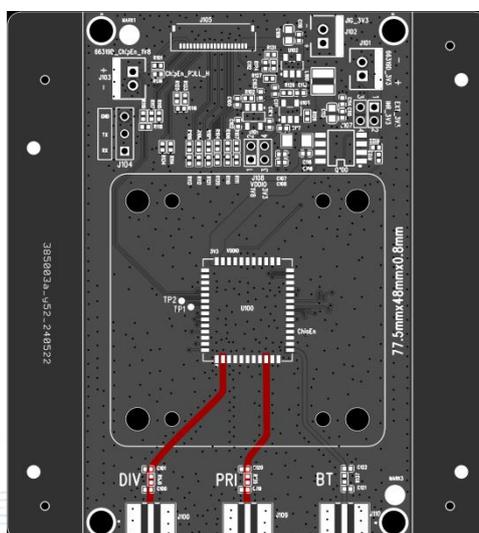
8.5 Trace Antenna Designs

Users should connect antennas to half hole pad through copper tube structure or FP types of RF trace and the trace impedance must be controlled in 50Ω. recommends that the total insertion loss between the antenna pads and antennas should meet

the following requirements:

Frequency	Loss
2400MHz-2500MHz	< 0.6dB
5150MHz-5850MHz	< 1.2dB

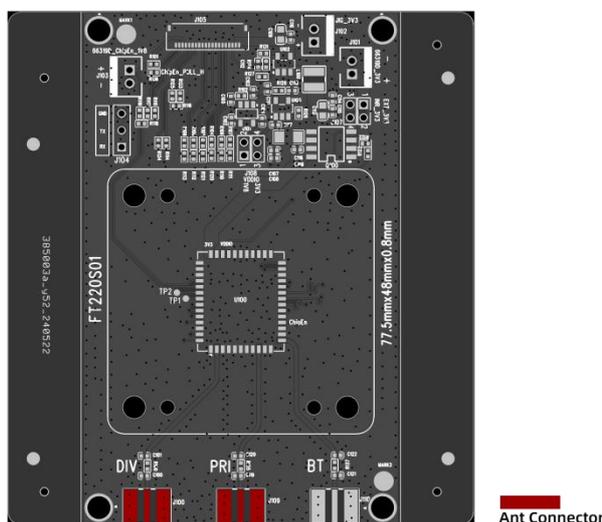
To facilitate the antenna tuning and certification test, a RF connector and an antenna matching circuit should be added. The following figure is the recommended circuit.



The module needs to be attached to the PCB board and connected to the external antenna through the solder joint of the circuit on the PCB. The gain of the external antenna is 2dB (i Max.) ,the internal structure is copper tube structure or FPC. A resistance of 0R is added between the module and the antenna at C1003 to ensure that the impedance of the connection between the module and the antenna reaches 50R.The J0800 position on the PCB is where the external antenna is connected.

RF traces layout

- 1.Keep the RF trace from module ant pin to antenna as short as possible
- 2.RF trace should be 50 Ω either on the top layer or in the inner layer
- 3.RF trace should be avoided right angle and sharp angle.
- 4.Put enough GND vias around RF traces.
- 5.RF trace should be far away from other high speed signal lines.



Parameters	Min	Typ	Max
External Antenna VSWR	1	1.6	2.0

8.6 RF Exposure Considerations

This device complies with FCC radiation exposure limits set forth for an uncontrolled environment. This equipment should be installed and operated with minimum distance 20cm between the radiator & your body

8.7 Antenna Type and Gain

The following antennas have been certified for use with this module.

Only antennas of the same type with equal or lower gain may also be used with this module.

Other types of antennas and/or higher gain antennas may require the additional authorization for operation.

Antenna Specification list below:

Model	Type	Connector	Peak gain (dBi)				
			2400-2483.5 MHz	5150-5250 MHz	5250-5350 MHz	5470-5725 MHz	5725-5850 MHz
FD7652P	External Antenna	/	2.00dBi	2.00dBi	2.00dBi	2.00dBi	2.00dBi

8.8 End Product Labelling Compliance Information

When the module is installed in the host device, the FCC ID label must be visible through a window on the final device or it must be visible when an access panel, door or cover is easily removed. If not, a second label must be placed on the outside of the final device

that contains the following text: “Contains FCC ID: 2BFAK-FD220S”. The FCC ID can be used only when all FCC compliance requirements are met

8.9 Information on Test Modes and Additional Testing Requirements

This transmitter is tested in a standalone mobile RF exposure condition and any co-located or simultaneous transmission with other transmitter(s) class II permissive change re-evaluation or new FCC authorization.

Host manufacturer installed this modular with single modular approval should perform the test of radiated emission and spurious emission according to FCC part 15C, Part 15E, 15.209, 15.207 requirement, only if the test result comply with FCC part 15C, Part 15E, 15.209, 15.207 requirement, then the host can be sold legally.

8.10 Additional testing, Part 15 Subpart B Disclaimer

This transmitter modular us tested as a subsystem and its certification does not cover the FCC Part 15 Subpart B rules requirement applicable to the final host. The final host will still need to be reassessed for compliance to this portion of rules requirements if applicable.

As long as all conditions above are met, further transmitter test will not be required. However, the OEM integrator is still responsible for testing their end-product for any additional compliance requirements required with this modular installed.

8.11 Manual Information to The End User

The OEM integrator has to be aware not to provide information to the end user regarding how to install or remove this RF module in the user's manual of the end product which integrates this module.

The host integrator must follow the integration instructions provided in this document and ensure that the composite system end product complies with the requirements by a technical assessment or evaluation to the rules and to KDB Publication 996369.

The host integrator installing this module into their product must ensure that the final composite product complies with the requirements by a technical assessment or evaluation to the rules, including the transmitter operation and should refer to guidance in KDB Publication 996369.

OEM/Host Manufacturer Responsibilities

OEM/Host manufacturers are ultimately responsible for the compliance of the Host and Module. The final product must be reassessed against all the essential requirements of the FCC rule such as FCC Part 15 Subpart B before it can be placed on the US market.

This includes reassessing the transmitter module for compliance with the Radio and RF Exposure essential requirements of the FCC rules.

8.12 How to Make Changes - Important Note

In the event that these conditions cannot be met (for example certain laptop configurations or co-location with another transmitter), then the FCC authorization is no longer considered valid and the FCC ID cannot be used on the final product. In these circumstances, the OEM integrator will be responsible for re-evaluating the end product (including the transmitter) and obtaining a separate FCC authorization.

9 Ordering, Storage, Production and Packaging

9.1 Ordering Model

The ordering information for the mentioned Wi-Fi modules is as follows:

Product	Model	Interface	Storage Temperature	Size
FD7652P	220P12-0	PCIE	-40°C~85°C	13mm*15mm

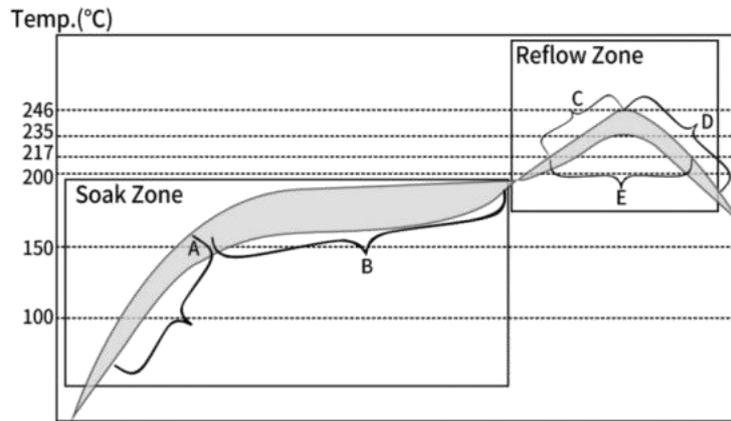
9.2 Storage Conditions

- ❖ FD7652P module is 3 (MSL3) and packed in a vacuum-sealed bag when shipped, the recommended storage temperature is $25\pm 5^{\circ}\text{C}$, and the relative humidity is 35%~60%. Under this condition, the module can be stored for 12 months.
- ❖ The Module shall be stored without opening the packing. After the packing opened, the module shall be completed the patch soldering within 24 hours.
- ❖ FD7652P module can be stored for no more than 168 hours in a workshop environment with a temperature of $25\pm 5^{\circ}\text{C}$, a relative humidity below 60% and in compliance with IPC/JEDEC J-STD-033. It is not recommended to expose the module unpacked to the air for a long time. If not immediately patch soldering, it is recommended to store the module in a moisture-proof cabinet with a relative humidity of less than 10% to keep the module dry.
- ❖ If the module is not stored according to the above recommended method, it needs to be baked at high temperature ($120\pm 5^{\circ}\text{C}$) for 8 hours. The re-baked module shall be patched within 24 hours.
- ❖ Please pay attention to ESD protection when unpacking and handling modules.

9.3 Production Welding

During the production welding process, please do not use any organic solvents (such as alcohol, isopropanol, acetone, trichloroethylene, etc.) to wipe the shield of the FD7652P module, otherwise it may cause the shield to rust. Please do not ultrasonically clean the module, it may cause damage to the crystal inside the module. Please make sure that the spray material used will not chemically react with the module shield or PCB and will not flow into the module when spraying modules.

In order to ensure the welding quality and reliability of the FD7652P module, the thickness of the printed stencil is recommended to be 0.15~0.18mm; the recommended reflow curve is as follows:



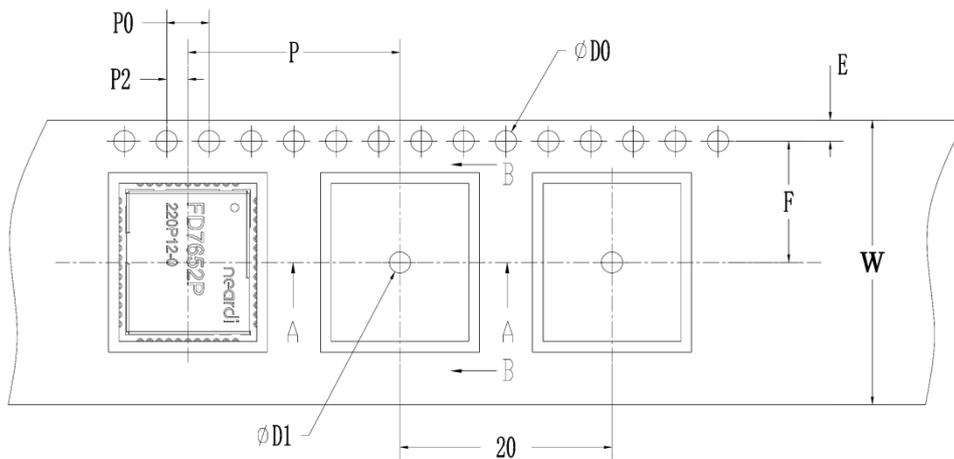
Recommended reflow curve

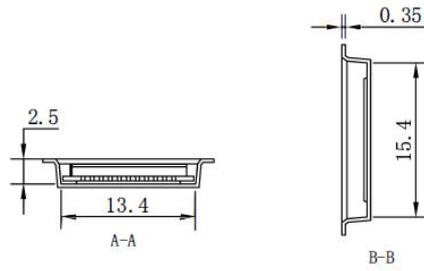
Item	Description	Value
Endothermic Zone Heating Rate	Interval A	≤3 °C/s
Soak time	From the end of interval A to the beginning of interval B	60~120s
Reflow Zone Heating Rate	Interval C	≤3 °C/s
Maximum Temperature	Highest point of the curve	246°C(+5/-0°C)
Cooling Rate	Interval D	<6 °C/s
Reflow Time	Interval E	60~150 seconds

9.4 Packing Specifications

The key parameters and packaging processes described in this chapter are for reference only. The appearance and structure of the specific packaging materials are subject to actual delivery.

9.4.1 Tape Dimensions

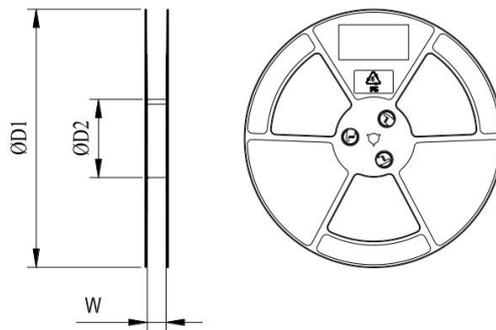




Tape dimensions

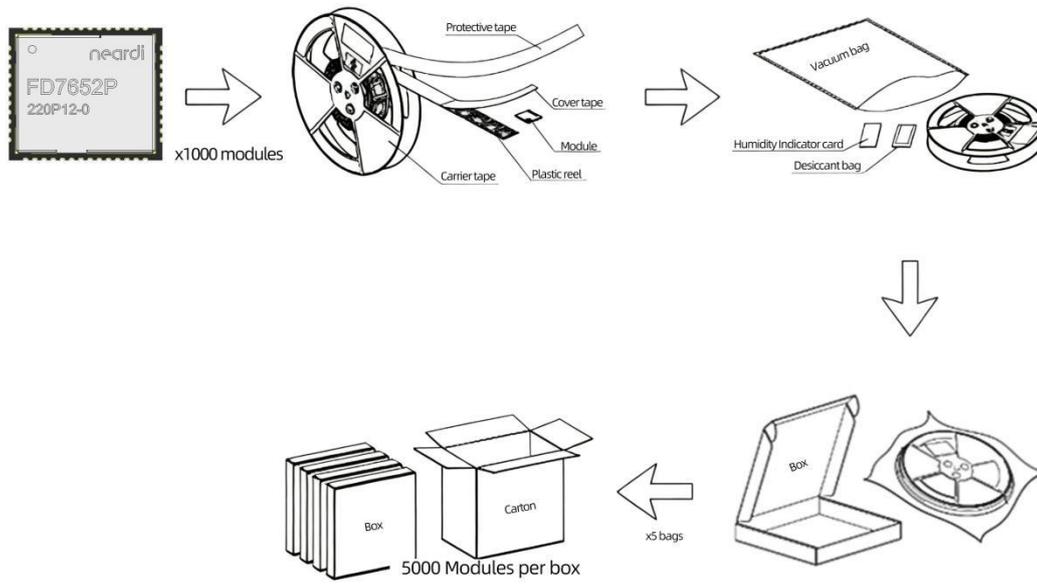
W	P	P0	P2	D0	D1	F	E.	Unit
24	20	4.0	2.0	1.5	1.5	11.5	1.75	mm

9.4.2 Plastic Reel Dimensions



ØD1	ØD2	W	unit
330	100	24	mm

9.4.3 Packaging Process



Package specification